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Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I ² C, IrDA, LINbus, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 12bit SAR; D/A 12bit
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32tg11b140f64gq64-a

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3. System Overview

3.1 Introduction

The Tiny Gecko Series 1 product family is well suited for any battery operated application as well as other systems requiring high performance and low energy consumption. This section gives a short introduction to the MCU system. The detailed functional description can be found in the Tiny Gecko Series 1 Reference Manual. Any behavior that does not conform to the specifications in this data sheet or the functional descriptions in the Tiny Gecko Series 1 Reference Manual are detailed in the EFM32TG11 Errata document.

A block diagram of the Tiny Gecko Series 1 family is shown in [Figure 3.1 Detailed EFM32TG11 Block Diagram on page 10](#). The diagram shows a superset of features available on the family, which vary by OPN. For more information about specific device features, consult [Ordering Information](#).

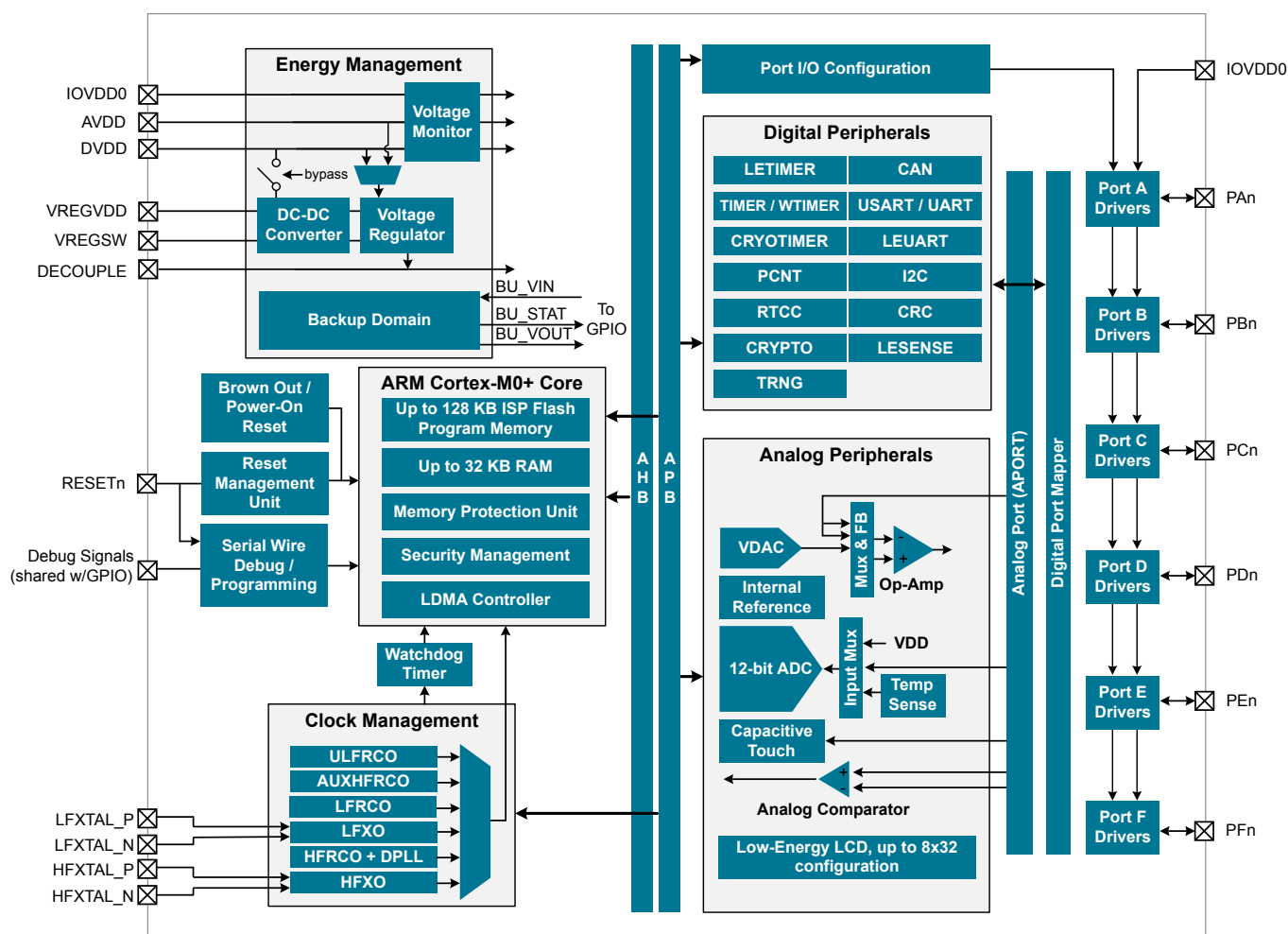


Figure 3.1. Detailed EFM32TG11 Block Diagram

3.3 General Purpose Input/Output (GPIO)

EFM32TG11 has up to 67 General Purpose Input/Output pins. Each GPIO pin can be individually configured as either an output or input. More advanced configurations including open-drain, open-source, and glitch-filtering can be configured for each individual GPIO pin. The GPIO pins can be overridden by peripheral connections, like SPI communication. Each peripheral connection can be routed to several GPIO pins on the device. The input value of a GPIO pin can be routed through the Peripheral Reflex System to other peripherals. The GPIO subsystem supports asynchronous external pin interrupts.

3.4 Clocking

3.4.1 Clock Management Unit (CMU)

The Clock Management Unit controls oscillators and clocks in the EFM32TG11. Individual enabling and disabling of clocks to all peripheral modules is performed by the CMU. The CMU also controls enabling and configuration of the oscillators. A high degree of flexibility allows software to optimize energy consumption in any specific application by minimizing power dissipation in unused peripherals and oscillators.

3.4.2 Internal and External Oscillators

The EFM32TG11 supports two crystal oscillators and fully integrates four RC oscillators, listed below.

- A high frequency crystal oscillator (HFXO) with integrated load capacitors, tunable in small steps, provides a precise timing reference for the MCU. Crystal frequencies in the range from 4 to 48 MHz are supported. An external clock source such as a TCXO can also be applied to the HFXO input for improved accuracy over temperature.
- A 32.768 kHz crystal oscillator (LFXO) provides an accurate timing reference for low energy modes.
- An integrated high frequency RC oscillator (HFRCO) is available for the MCU system. The HFRCO employs fast startup at minimal energy consumption combined with a wide frequency range. When crystal accuracy is not required, it can be operated in free-running mode at a number of factory-calibrated frequencies. A digital phase-locked loop (DPLL) feature allows the HFRCO to achieve higher accuracy and stability by referencing other available clock sources such as LFXO and HFXO.
- An integrated auxiliary high frequency RC oscillator (AUXHFRCO) is available for timing the general-purpose ADC with a wide frequency range.
- An integrated low frequency 32.768 kHz RC oscillator (LFRCO) can be used as a timing reference in low energy modes, when crystal accuracy is not required.
- An integrated ultra-low frequency 1 kHz RC oscillator (ULFRCO) is available to provide a timing reference at the lowest energy consumption in low energy modes.

3.5 Counters/Timers and PWM

3.5.1 Timer/Counter (TIMER)

TIMER peripherals keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each TIMER is a 16-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the TIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit TIMER_0 only.

3.5.2 Wide Timer/Counter (WTIMER)

WTIMER peripherals function just as TIMER peripherals, but are 32 bits wide. They keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. The core of each WTIMER is a 32-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the WTIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit WTIMER_0 only.

3.5.3 Real Time Counter and Calendar (RTCC)

The Real Time Counter and Calendar (RTCC) is a 32-bit counter providing timekeeping in all energy modes. The RTCC includes a Binary Coded Decimal (BCD) calendar mode for easy time and date keeping. The RTCC can be clocked by any of the on-board oscillators with the exception of the AUXHFRCO, and it is capable of providing system wake-up at user defined instances. The RTCC includes 128 bytes of general purpose data retention, allowing easy and convenient data storage in all energy modes down to EM4H.

	0xffffffe				
	0xf1000000			AAP	0xf0e01000
Device	0xf0ffffff				0xf0e00000
	0xf0000000			CM0+ ROM Table	0xf0100000
	0xefffffff				0xf00ff000
	0xe0100000				0xf0000000
	0xe000ffff				
CM0+ Peripherals	0xe0000000				
	0xdfffffff				
	0x460f0400			System Control Space	0xe000f000
	0x460f03ff				0xe000e000
Bit Set (Peripherals / CRYPTO0)	0x46000000				0xe0003000
	0x45ffffff			BPU	0xe0002000
	0x440f0400			DWT	0xe0001000
	0x440f03ff				0xe0000000
Bit Clear (Peripherals / CRYPTO0)	0x44000000				
	0x43ffffff				
	0x400f0400				
CRYPTO0	0x400f03ff				
	0x400f0000			RAM0 (code space)	0x10008000
Peripherals 1	0x400effff				0x10000000
	0x40040000			Chip config	0x0fe08400
Peripherals 0	0x4003ffff				0x0fe08000
	0x40000000			Lock bits	0x0fe04800
	0x3fffffff				0x0fe04000
	0x20000000				0x0fe00800
RAM0 (data space)	0x20007fff			User Data	0x0fe00000
	0x20000000				0x00020000
	0x1fffffff				
Code				Flash (128 KB)	
	0x00000000				0x00000000

Figure 3.2. EFM32TG11 Memory Map — Core Peripherals and Code Space

4.1.4 DC-DC Converter

Test conditions: L_DCDC=4.7 μ H (Murata LQH3NPN4R7MM0L), C_DCDC=4.7 μ F (Samsung CL10B475KQ8NQNC), V_DCDC_I=3.3 V, V_DCDC_O=1.8 V, I_DCDC_LOAD=50 mA, Heavy Drive configuration, F_DCDC_LN=7 MHz, unless otherwise indicated.

Table 4.4. DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V _{DCDC_I}	Bypass mode, I _{DCDC_LOAD} = 50 mA	1.8	—	V _{VREGVDD_MAX}	V
		Low noise (LN) mode, 1.8 V output, I _{DCDC_LOAD} = 100 mA, or Low power (LP) mode, 1.8 V output, I _{DCDC_LOAD} = 10 mA	2.4	—	V _{VREGVDD_MAX}	V
		Low noise (LN) mode, 1.8 V output, I _{DCDC_LOAD} = 200 mA	2.6	—	V _{VREGVDD_MAX}	V
Output voltage programmable range ¹	V _{DCDC_O}		1.8	—	V _{VREGVDD}	V
Regulation DC accuracy	ACC _{DC}	Low Noise (LN) mode, 1.8 V target output	TBD	—	TBD	V
Regulation window ⁴	WIN _{REG}	Low Power (LP) mode, LPCMPBIASEM _{xx} ³ = 0, 1.8 V target output, I _{DCDC_LOAD} ≤ 75 μ A	TBD	—	TBD	V
		Low Power (LP) mode, LPCMPBIASEM _{xx} ³ = 3, 1.8 V target output, I _{DCDC_LOAD} ≤ 10 mA	TBD	—	TBD	V
Steady-state output ripple	V _R		—	3	—	mV _{pp}
Output voltage under/overshoot	V _{OV}	CCM Mode (LNFORCECCM ³ = 1), Load changes between 0 mA and 100 mA	—	25	TBD	mV
		DCM Mode (LNFORCECCM ³ = 0), Load changes between 0 mA and 10 mA	—	45	TBD	mV
		Overshoot during LP to LN CCM/DCM mode transitions compared to DC level in LN mode	—	200	—	mV
		Undershoot during BYP/LP to LN CCM (LNFORCECCM ³ = 1) mode transitions compared to DC level in LN mode	—	40	—	mV
		Undershoot during BYP/LP to LN DCM (LNFORCECCM ³ = 0) mode transitions compared to DC level in LN mode	—	100	—	mV
DC line regulation	V _{REG}	Input changes between V _{VREGVDD_MAX} and 2.4 V	—	0.1	—	%
DC load regulation	I _{REG}	Load changes between 0 mA and 100 mA in CCM mode	—	0.1	—	%

4.1.9 Oscillators

4.1.9.1 Low-Frequency Crystal Oscillator (LFXO)

Table 4.11. Low-Frequency Crystal Oscillator (LFXO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Crystal frequency	f_{LFXO}		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	ESR_{LFXO}		—	—	70	k Ω
Supported range of crystal load capacitance ¹	C_{LFXO_CL}		6	—	18	pF
On-chip tuning cap range ²	C_{LFXO_T}	On each of LFX TAL_N and LFX TAL_P pins	8	—	40	pF
On-chip tuning cap step size	SS_{LFXO}		—	0.25	—	pF
Current consumption after startup ³	I_{LFXO}	ESR = 70 k Ω m, C_L = 7 pF, GAIN ⁴ = 2, AGC ⁴ = 1	—	273	—	nA
Start- up time	t_{LFXO}	ESR = 70 k Ω m, C_L = 7 pF, GAIN ⁴ = 2	—	308	—	ms

Note:

1. Total load capacitance as seen by the crystal.
2. The effective load capacitance seen by the crystal will be $C_{LFXO_T} / 2$. This is because each XTAL pin has a tuning cap and the two caps will be seen in series by the crystal.
3. Block is supplied by AVDD if ANASW = 0, or DVDD if ANASW=1 in EMU_PWRCTRL register.
4. In CMU_LFXOCTRL register.

4.1.9.5 Auxiliary High-Frequency RC Oscillator (AUXHFRCO)

Table 4.15. Auxiliary High-Frequency RC Oscillator (AUXHFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency accuracy	$f_{\text{AUXHFRCO_ACC}}$	At production calibrated frequencies, across supply voltage and temperature	TBD	—	TBD	%
Start-up time	t_{AUXHFRCO}	$f_{\text{AUXHFRCO}} \geq 19 \text{ MHz}$	—	400	—	ns
		$4 < f_{\text{AUXHFRCO}} < 19 \text{ MHz}$	—	1.4	—	μs
		$f_{\text{AUXHFRCO}} \leq 4 \text{ MHz}$	—	2.5	—	μs
Current consumption on all supplies	I_{AUXHFRCO}	$f_{\text{AUXHFRCO}} = 48 \text{ MHz}$	—	238	TBD	μA
		$f_{\text{AUXHFRCO}} = 38 \text{ MHz}$	—	196	TBD	μA
		$f_{\text{AUXHFRCO}} = 32 \text{ MHz}$	—	160	TBD	μA
		$f_{\text{AUXHFRCO}} = 26 \text{ MHz}$	—	137	TBD	μA
		$f_{\text{AUXHFRCO}} = 19 \text{ MHz}$	—	110	TBD	μA
		$f_{\text{AUXHFRCO}} = 16 \text{ MHz}$	—	101	TBD	μA
		$f_{\text{AUXHFRCO}} = 13 \text{ MHz}$	—	78	TBD	μA
		$f_{\text{AUXHFRCO}} = 7 \text{ MHz}$	—	54	TBD	μA
		$f_{\text{AUXHFRCO}} = 4 \text{ MHz}$	—	30	TBD	μA
		$f_{\text{AUXHFRCO}} = 2 \text{ MHz}$	—	27	TBD	μA
		$f_{\text{AUXHFRCO}} = 1 \text{ MHz}$	—	25	TBD	μA
Coarse trim step size (% of period)	$SS_{\text{AUXHFRCO_COARSE}}$		—	0.8	—	%
Fine trim step size (% of period)	$SS_{\text{AUXHFRCO_FINE}}$		—	0.1	—	%
Period jitter	PJ_{AUXHFRCO}		—	0.2	—	% RMS

4.1.9.6 Ultra-low Frequency RC Oscillator (ULFRCO)

Table 4.16. Ultra-low Frequency RC Oscillator (ULFRCO)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	f_{ULFRCO}		TBD	1	TBD	kHz

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current, continuous conversions, WARMUP-MODE=KEEPCSENWARM	I _{CSEN_ACTIVE}	SAR or Delta Modulation conversions of 33 pF capacitor, CS0CG=0 (Gain = 10x), always on	—	90.5	—	μA
HFPERCLK supply current	I _{CSEN_HFPERCLK}	Current contribution from HFPERCLK when clock to CSEN block is enabled.	—	2.25	—	μA/MHz

Note:

1. Current is specified with a total external capacitance of 33 pF per channel. Average current is dependent on how long the module is actively sampling channels within the scan period, and scales with the number of samples acquired. Supply current for a specific application can be estimated by multiplying the current per sample by the total number of samples per period ($\text{total_current} = \text{single_sample_current} * (\text{number_of_channels} * \text{accumulation})$).

4.1.22 USART SPI

SPI Master Timing

Table 4.31. SPI Master Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCLK period ^{1 3 2}	t_{SCLK}		$2 * t_{\text{HFERCLK}}$	—	—	ns
CS to MOSI ^{1 3}	$t_{\text{CS_MO}}$		-19.8	—	18.9	ns
SCLK to MOSI ^{1 3}	$t_{\text{SCLK_MO}}$		-10	—	14.5	ns
MISO setup time ^{1 3}	$t_{\text{SU_MI}}$	IOVDD = 1.62 V	75	—	—	ns
		IOVDD = 3.0 V	40	—	—	ns
MISO hold time ^{1 3}	$t_{\text{H_MI}}$		-10	—	—	ns

Note:

1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0).
2. t_{HFERCLK} is one period of the selected HFERCLK.
3. Measurement done with 8 pF output loading at 10% and 90% of V_{DD} (figure shows 50% of V_{DD}).

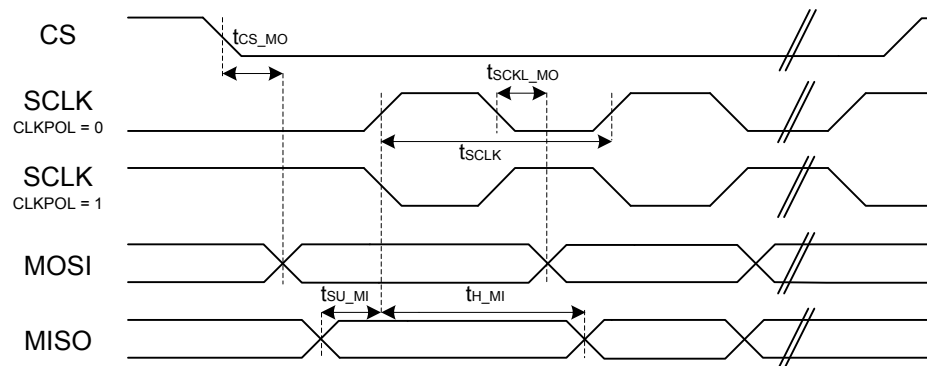


Figure 4.1. SPI Master Timing Diagram

5.4 EFM32TG11B3xx in QFP64 Device Pinout

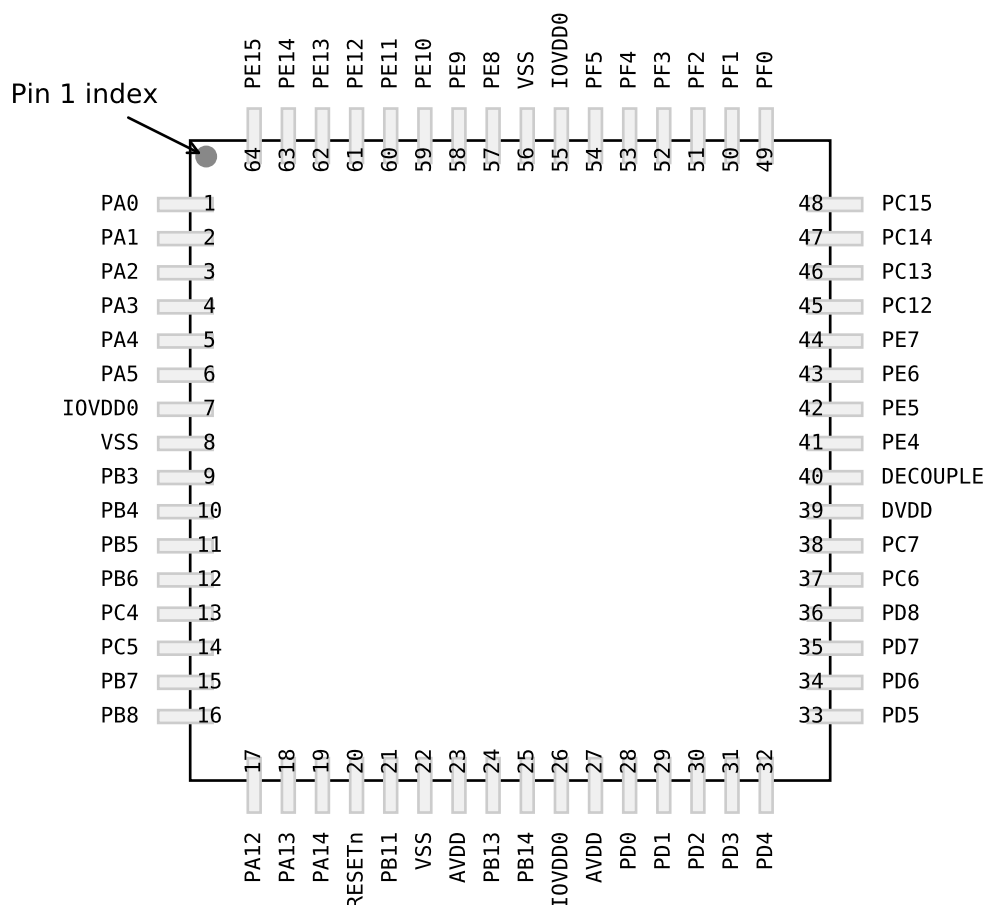


Figure 5.4. EFM32TG11B3xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.14 GPIO Functionality Table](#) or [5.15 Alternate Functionality Overview](#).

Table 5.4. EFM32TG11B3xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB4	10	GPIO	PB5	11	GPIO
PB6	12	GPIO	PC4	13	GPIO
PC5	14	GPIO	PB7	15	GPIO
PB8	16	GPIO	PA8	17	GPIO
PA12	18	GPIO	PA13	19	GPIO (5V)
PA14	20	GPIO	RESETn	21	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	22	GPIO	PB12	23	GPIO
AVDD	24 28	Analog power supply.	PB13	25	GPIO
PB14	26	GPIO	PD0	29	GPIO (5V)
PD1	30	GPIO	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC7	37	GPIO
VREGSW	39	DCDC regulator switching node	VREGVDD	40	Voltage regulator VDD input
DVDD	41	Digital power supply.	DECOUPLE	42	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	43	GPIO	PE5	44	GPIO
PE6	45	GPIO	PE7	46	GPIO
PC12	47	GPIO (5V)	PC13	48	GPIO (5V)
PF0	49	GPIO (5V)	PF1	50	GPIO (5V)
PF2	51	GPIO	PF3	52	GPIO
PF4	53	GPIO	PF5	54	GPIO
PE8	56	GPIO	PE9	57	GPIO
PE10	58	GPIO	PE11	59	GPIO
PE12	60	GPIO	PE13	61	GPIO
PE14	62	GPIO	PE15	63	GPIO
PA15	64	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LCD_COM0	0: PE4		LCD driver common line number 0.
LCD_COM1	0: PE5		LCD driver common line number 1.
LCD_COM2	0: PE6		LCD driver common line number 2.
LCD_COM3	0: PE7		LCD driver common line number 3.
LCD_SEG0	0: PF2		LCD segment line 0.
LCD_SEG1	0: PF3		LCD segment line 1.
LCD_SEG2	0: PF4		LCD segment line 2.
LCD_SEG3	0: PF5		LCD segment line 3.
LCD_SEG4	0: PE8		LCD segment line 4.
LCD_SEG5	0: PE9		LCD segment line 5.
LCD_SEG6	0: PE10		LCD segment line 6.
LCD_SEG7	0: PE11		LCD segment line 7.
LCD_SEG8	0: PE12		LCD segment line 8.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LCD_SEG35	0: PC9		LCD segment line 35.
LES_ALTEX0	0: PD6		LESENSE alternate excite output 0.
LES_ALTEX1	0: PD7		LESENSE alternate excite output 1.
LES_ALTEX2	0: PA3		LESENSE alternate excite output 2.
LES_ALTEX3	0: PA4		LESENSE alternate excite output 3.
LES_ALTEX4	0: PA5		LESENSE alternate excite output 4.
LES_ALTEX5	0: PE11		LESENSE alternate excite output 5.
LES_ALTEX6	0: PE12		LESENSE alternate excite output 6.
LES_ALTEX7	0: PE13		LESENSE alternate excite output 7.
LES_CH0	0: PC0		LESENSE channel 0.
LES_CH1	0: PC1		LESENSE channel 1.
LES_CH2	0: PC2		LESENSE channel 2.
LES_CH3	0: PC3		LESENSE channel 3.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
U0_TX	2: PA3 3: PC14	4: PC4 5: PF1 6: PD7	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	0: PE12 1: PE5 2: PC9 3: PC15	4: PB13 5: PA12	USART0 clock input / output.
US0_CS	0: PE13 1: PE4 2: PC8 3: PC14	4: PB14 5: PA13	USART0 chip select input / output.
US0_CTS	0: PE14 2: PC7 3: PC13	4: PB6 5: PB11	USART0 Clear To Send hardware flow control input.
US0_RTS	0: PE15 2: PC6 3: PC12	4: PB5 5: PD6	USART0 Request To Send hardware flow control output.
US0_RX	0: PE11 1: PE6 2: PC10 3: PE12	4: PB8 5: PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	0: PE10 1: PE7 2: PC11 3: PE13	4: PB7 5: PC0	USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	0: PB7 1: PD2 2: PF0 3: PC15	4: PC3 5: PB11 6: PE5	USART1 clock input / output.
US1_CS	0: PB8 1: PD3 2: PF1 3: PC14	4: PC0 5: PE4	USART1 chip select input / output.
US1_CTS	1: PD4 2: PF3 3: PC6	4: PC12 5: PB13	USART1 Clear To Send hardware flow control input.
US1_RTS	1: PD5 2: PF4 3: PC7	4: PC13 5: PB14	USART1 Request To Send hardware flow control output.
US1_RX	0: PC1 1: PD1 2: PD6	4: PC2 5: PA0 6: PA2	USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	0: PC0 1: PD0 2: PD7	4: PC1 5: PF2 6: PA14	USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US2_CLK	0: PC4 1: PB5 2: PA9 3: PA15	5: PF2	USART2 clock input / output.
US2_CS	0: PC5 1: PB6 2: PA10 3: PB11	5: PF5	USART2 chip select input / output.
US2_CTS	0: PC1 1: PB12	4: PC12 5: PD6	USART2 Clear To Send hardware flow control input.
US2_RTS	0: PC0 2: PA12 3: PC14	4: PC13 5: PD8	USART2 Request To Send hardware flow control output.
US2_RX	0: PC3 1: PB4 2: PA8 3: PA14	5: PF1	USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	0: PC2 1: PB3 3: PA13	5: PF0	USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
US3_CLK	0: PA2 1: PD7 2: PD4		USART3 clock input / output.
US3_CS	0: PA3 1: PE4 2: PC14 3: PC0		USART3 chip select input / output.
US3_CTS	0: PA4 1: PE5 2: PD6		USART3 Clear To Send hardware flow control input.
US3_RTS	0: PA5 1: PC1 2: PA14 3: PC15		USART3 Request To Send hardware flow control output.
US3_RX	0: PA1 1: PE7 2: PB7		USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PA0 1: PE6 2: PB3		USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
VDAC0_EXT	0: PD6		Digital to analog converter VDAC0 external reference input pin.

The Analog Port (APORT) is an infrastructure used to connect chip pins with on-chip analog clients such as analog comparators, ADCs, DACs, etc. The APORT consists of a set of shared buses, switches, and control logic needed to configurably implement the signal routing. [Figure 5.14 APORT Connection Diagram on page 119](#) shows the APORT routing for this device family (note that available features may vary by part number). A complete description of APORT functionality can be found in the Reference Manual.

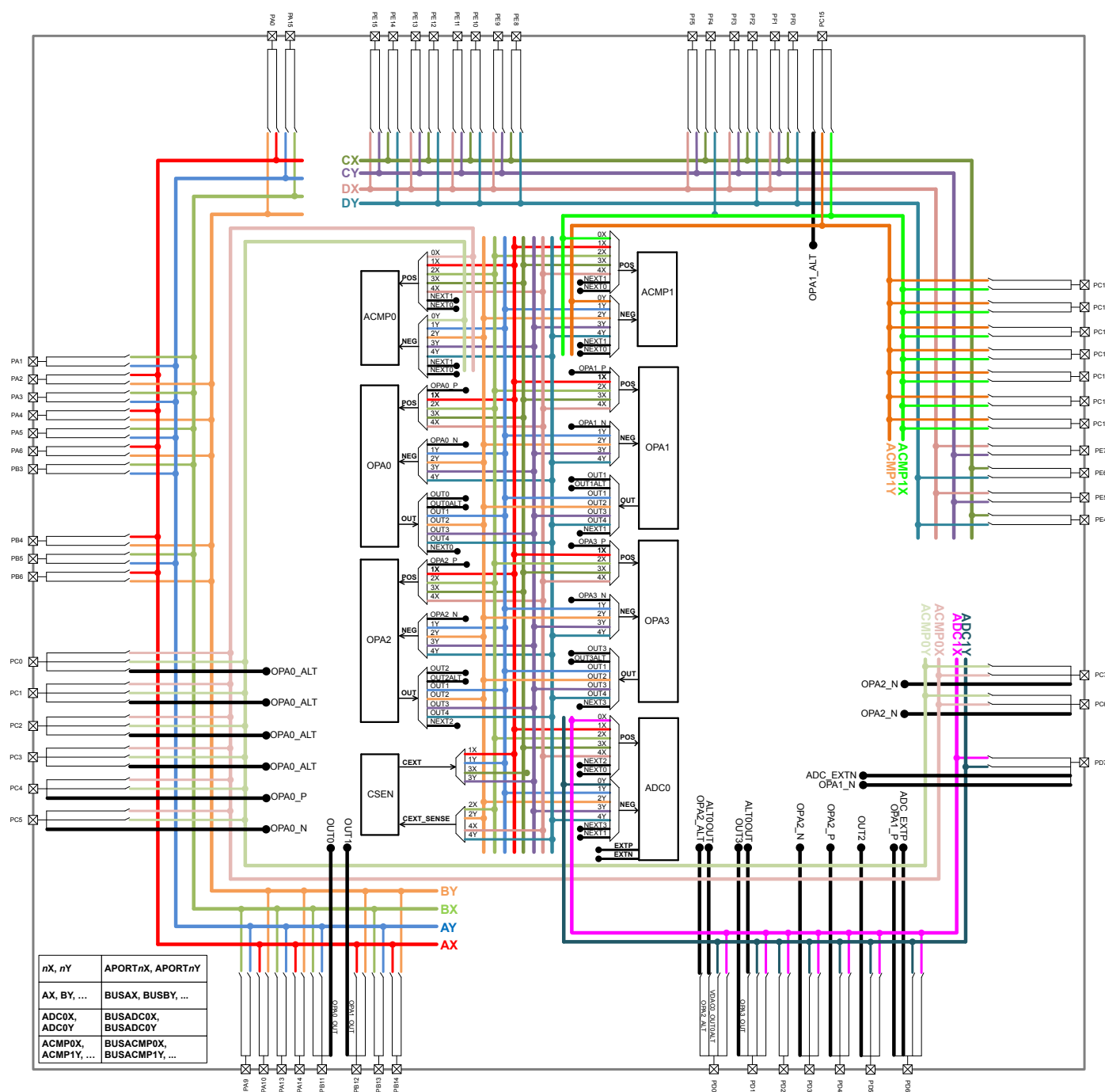


Figure 5.14. APORT Connection Diagram

Client maps for each analog circuit using the APORT are shown in the following tables. The maps are organized by bus, and show the peripheral's port connection, the shared bus, and the connection from specific bus channel numbers to GPIO pins.

In general, enumerations for the pin selection field in an analog peripheral's register can be determined by finding the desired pin connection in the table and then combining the value in the Port column (APORT_{pin}), and the channel identifier (CH_{pin}). For example, if pin

PF7 is available on port APORT2X as CH23, the register field enumeration to connect to PF7 would be APORT2XCH23. The shared bus used by this connection is indicated in the Bus column.

Table 5.16. ACMP0 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDY	BUSDY	BUSCY	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP0Y	BUSACMP0X	Bus
										CH31
				PB14			PB14			CH30
					PB13	PB13				CH29
				PB12			PB12			CH28
					PB11	PB11				CH27
										CH26
										CH25
										CH24
										CH23
				PB6			PB6			CH22
	PF5	PF5			PB5	PB5				CH21
PF4			PF4	PB4			PB4			CH20
	PF3	PF3			PB3	PB3				CH19
PF2			PF2							CH18
	PF1	PF1								CH17
PF0			PF0							CH16
	PE15	PE15			PA15	PA15				CH15
PE14			PE14	PA14			PA14			CH14
	PE13	PE13			PA13	PA13				CH13
PE12			PE12							CH12
	PE11	PE11								CH11
PE10			PE10	PA10			PA10			CH10
	PE9	PE9			PA9	PA9				CH9
PE8			PE8							CH8
	PE7	PE7						PC7	PC7	CH7
PE6			PE6	PA6			PA6	PC6	PC6	CH6
	PE5	PE5			PA5	PA5		PC5	PC5	CH5
PE4			PE4	PA4			PA4	PC4	PC4	CH4
					PA3	PA3		PC3	PC3	CH3
				PA2			PA2	PC2	PC2	CH2
					PA1	PA1		PC1	PC1	CH1
				PA0			PA0	PC0	PC0	CH0

[illegible]

8.2 TQFP64 PCB Land Pattern

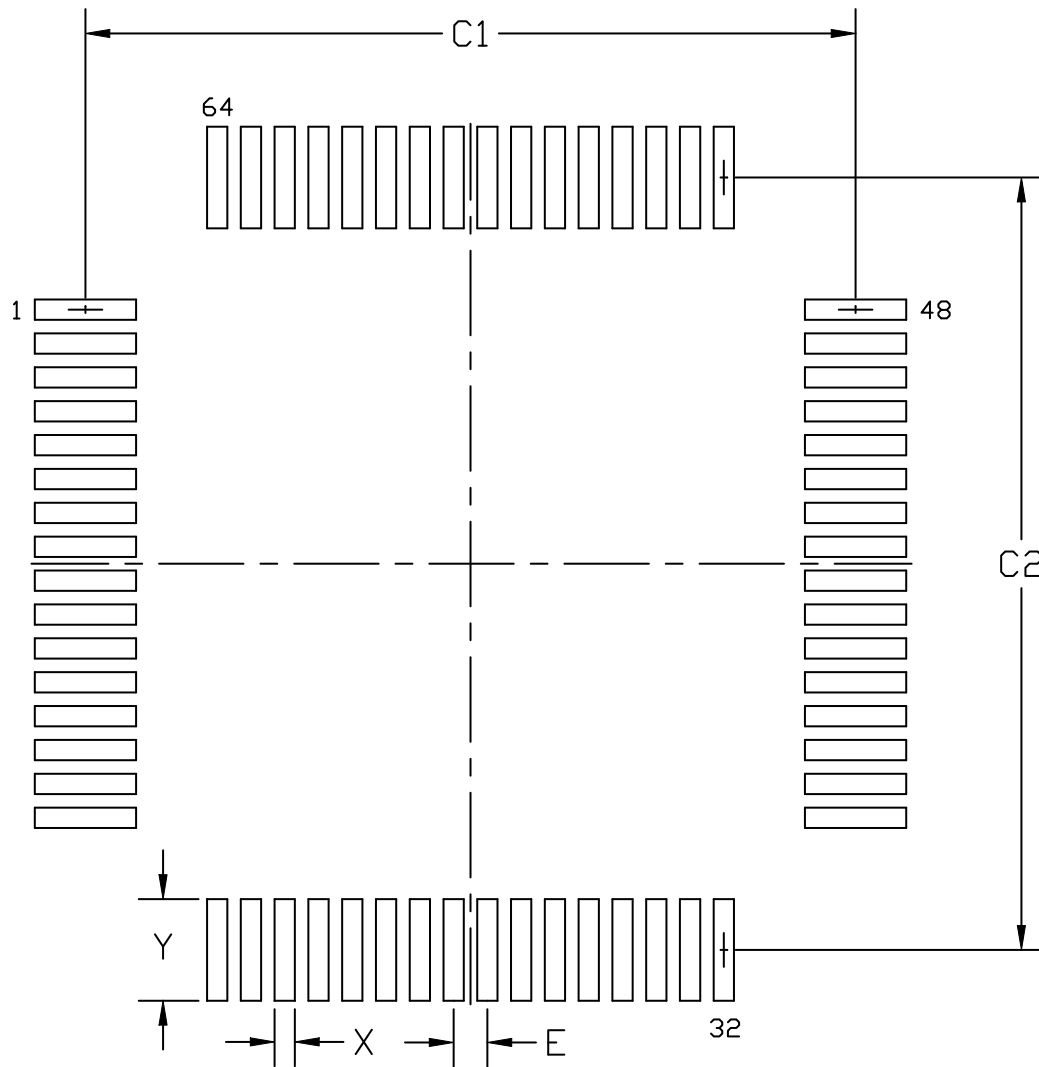


Figure 8.2. TQFP64 PCB Land Pattern Drawing

9.2 QFN64 PCB Land Pattern

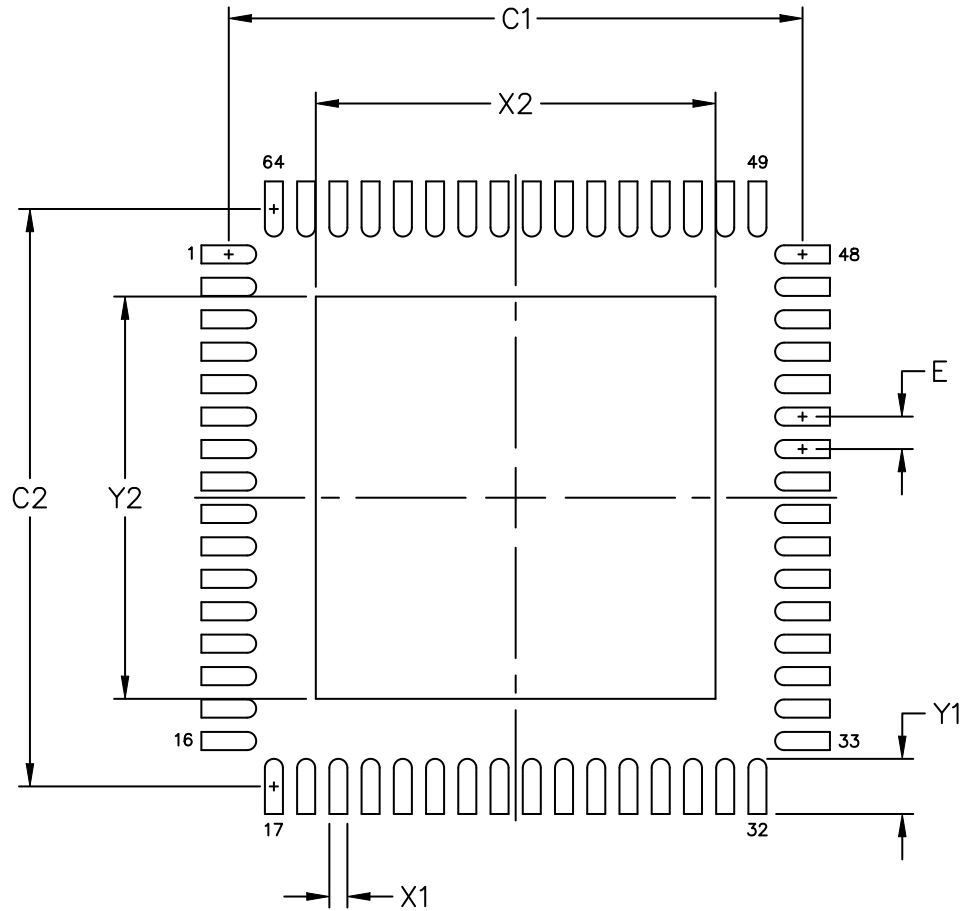


Figure 9.2. QFN64 PCB Land Pattern Drawing